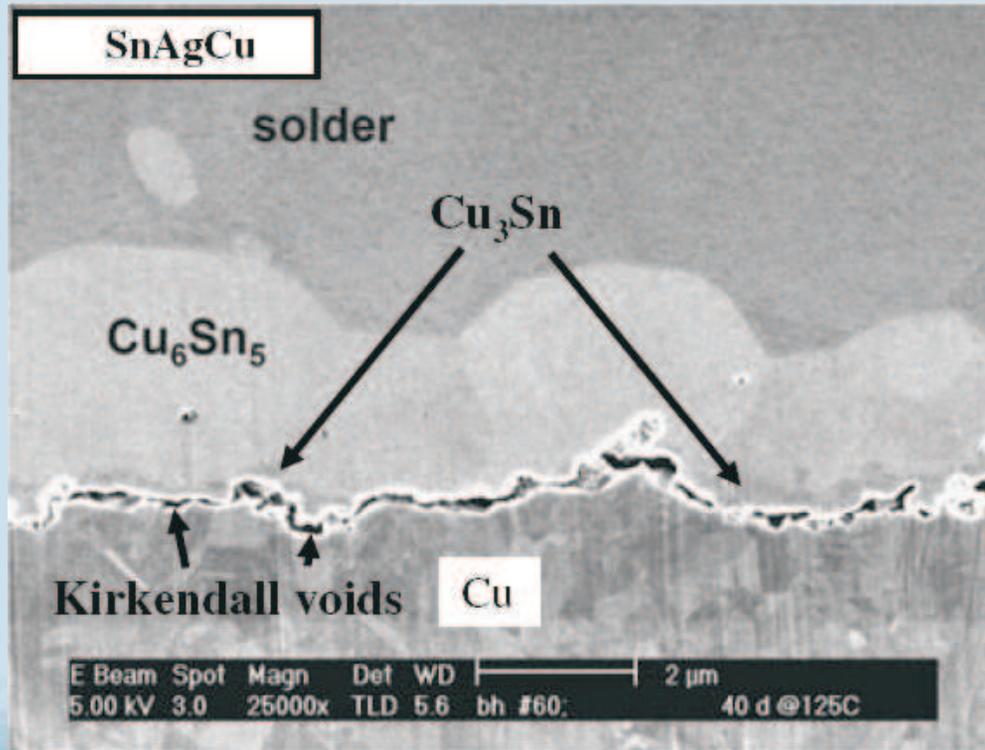




Modeling IMC growth in leadfree solder joints using the phase-field method coupled with the COST-531 thermodynamic database

Nele Moelans, A. Durga, Yuanyuan Guan
Bo Sundman, Alan Dinsdale, Suzana Fries

Final COST MP0602 meeting, June 22 - 24, BRNO



[J. Mater Sci: Mater. Electron (2007) 18:155]

- ◆ IMC-layers, IMC precipitates, voids, stresses, cracks ...during solidification and coarsening

- GP4: Modeling of microstructure evolution in the interdiffusion zone
- Use COST-531 thermodynamic database in phase-field simulations

- Phase-field model
- COST - 531 database
- 4 approaches to model phases with low solubility
 - ◆ Model I: Stoichiometric
 - ◆ Model II: Parabolic composition dependence
 - ◆ Model II: Order-disorder model
 - ◆ Model IV: Extended sublattice representation
- Concluding remarks

Phase-Field Model: Variables

(Sn)-solder $x_{Sn,eq} = 0.999$ $\eta_{(Sn),i}$
$\left\{ \begin{array}{l} Cu_6Sn_5 \\ x_{Sn,eq} = 0.45 \end{array} \right.$ $\eta_{Cu_6Sn_5,i}$
Cu_3Sn $x_{Sn,eq} = 0.25$ $\eta_{Cu_3Sn,i}$
(Cu)-substrate $x_{Sn,eq} = 0.05$ $\eta_{(Cu),i}$

- Grains and phases

$$\eta_{bct,1}, \eta_{bct,2}, \dots, \eta_{bct,i}(x, y, z, t), \dots$$

$$\eta_{Cu_6Sn_5,1}, \dots$$

$$\eta_{Cu_3Sn,1}, \dots$$

$$\eta_{fcc,1}, \dots$$

$$\eta_{Ag_3Sn,1}, \dots$$

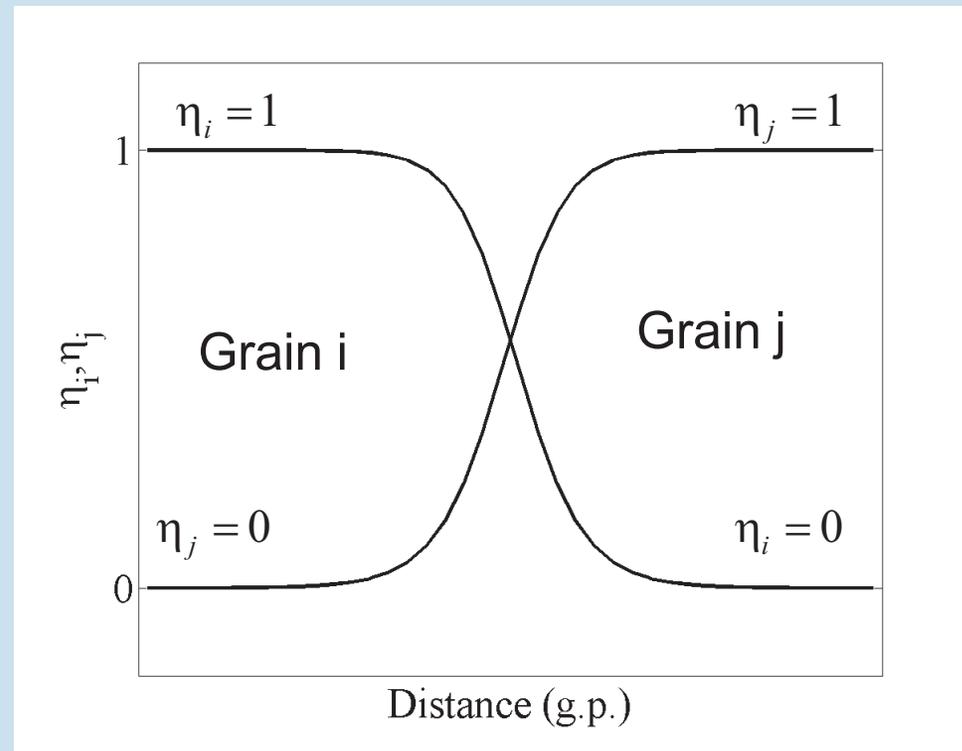
with $(\eta_{bct,1}, \eta_{bct,1}, \dots, \eta_{\rho,i}, \dots) = (1, 0, \dots, 0, \dots), (0, 1, \dots, 0, \dots), \dots, (0, 0, \dots, 1, \dots)$

- Composition: $x_{Cu}, x_{Sn}, (x_{Ag} = 1 - x_{Cu} - x_{Sn})$

Phase-Field Model: Diffuse interface

(Sn)-solder $x_{Sn,eq} = 0.999$ $\eta_{(Sn),i}$
$\left\{ \begin{array}{l} \text{Cu}_6\text{Sn}_5 \\ x_{Sn,eq} = 0.45 \end{array} \right.$ $\eta_{\text{Cu}_6\text{Sn}_5,i}$
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(Cu)-substrate $x_{Sn,eq} = 0.05$ $\eta_{(Cu),i}$

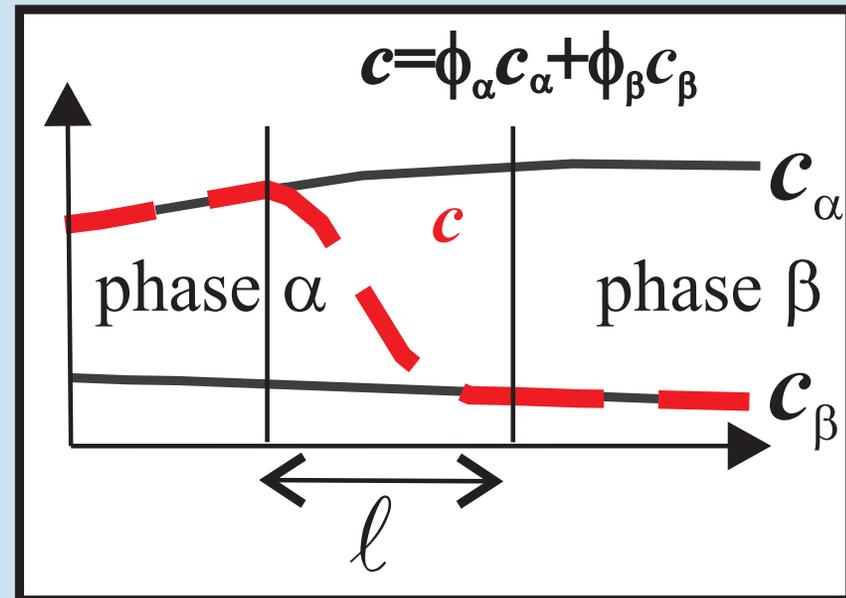
- $\eta_{bct,i}, \eta_{\text{Cu}_6\text{Sn}_5,i}, \eta_{\text{Cu}_3\text{Sn},i}, \eta_{fcc,i}, \eta_{\text{Ag}_3\text{Sn},i}$



Phase-Field Model: Diffuse interface

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$\left\{ \begin{array}{l} \text{Cu}_6\text{Sn}_5 \\ x_{Sn,eq} = 0.45 \\ \eta_{\text{Cu}_6\text{Sn}_5,i} \end{array} \right.$
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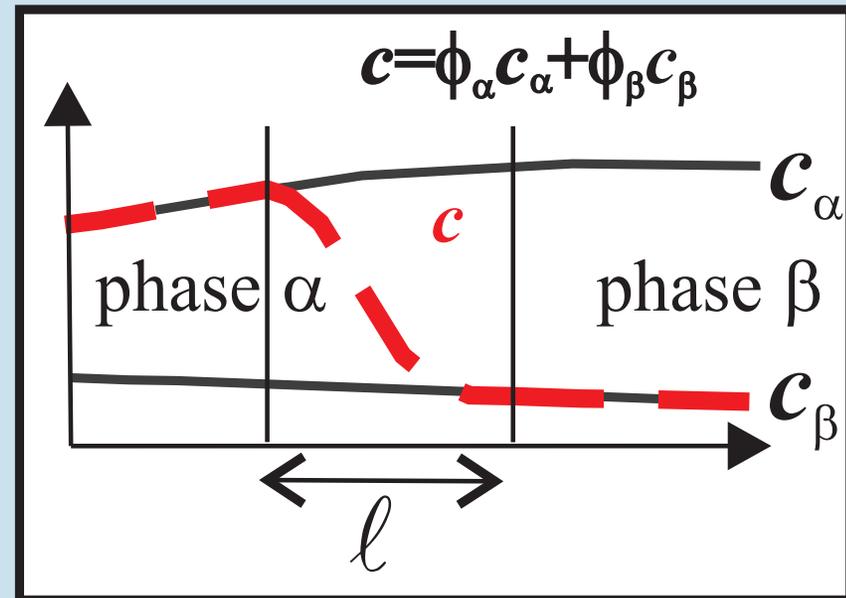
- Interface : Mixture of 2 phases



Phase-Field Model: Diffuse interface

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- Interface : Mixture of 2 phases



- Phase fractions $\phi_\rho = \frac{\sum_i \eta_{\rho,i}}{\sum_\sigma \sum_i \eta_{\sigma,i}}$
- Phase compositions $x_k^\rho(x_k, \phi_\rho)$

Phase-Field Model: Free energy functional

<p>(Sn)-solder $x_{Sn,eq} = 0.999$</p> <p>$\eta_{(Sn),i}$</p>
<p>$\left\{ \begin{array}{l} \text{Cu}_6\text{Sn}_5 \\ x_{Sn,eq} = 0.45 \end{array} \right.$</p> <p>$\eta_{\text{Cu}_6\text{Sn}_5,i}$</p>
<p>Cu_3Sn $x_{Sn,eq} = 0.25$</p> <p>$\eta_{\text{Cu}_3\text{Sn},i}$</p>
<p>(Cu)-substrate $x_{Sn,eq} = 0.05$</p> <p>$\eta_{(Cu),i}$</p>

$$F_{total} = \int_V f_{int}(\eta_{\rho,i}, \nabla \eta_{\rho,i}) dV + \int_V f_{bulk}(\eta_{\rho,i}, x_k) dV$$

Phase-Field Model: Free energy functional

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■ Bulk contribution

$$f_{bulk} = \sum_{\rho} \phi_{\rho} f^{\rho}(x_k^{\rho}) = \sum_{\rho} \phi_{\rho} \frac{G_m^{\rho}(x_k^{\rho})}{V_m}$$

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◆ Phase fractions $\phi_{\rho} = \frac{\sum_i \eta_{\rho,i}}{\sum_{\sigma} \sum_i \eta_{\sigma,i}}$

Phase-Field Model: Free energy functional

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■ Bulk contribution

$$f_{bulk} = \sum_{\rho} \phi_{\rho} f^{\rho}(x_k^{\rho}) = \sum_{\rho} \phi_{\rho} \frac{G_m^{\rho}(x_k^{\rho})}{V_m}$$

- ◆ Phase fractions $\phi_{\rho} = \frac{\sum_i \eta_{\rho,i}}{\sum_{\sigma} \sum_i \eta_{\sigma,i}}$
- ◆ Phase compositions $x_k^{\rho}(x_k, \phi_{\rho})$

■ Diffusion

$$\frac{\partial x_k}{\partial t} = \nabla \cdot \left[\sum_l \left[\left(\sum_\rho \phi_\rho M_{kl}^\rho \right) \nabla \left(\frac{\partial f^\rho}{\partial x_l^\rho} \right) \right] \right]$$

- ◆ Within each phase: $\frac{\partial x_k}{\partial t} = \nabla \cdot \left[\sum_l \left[\left(\frac{M_{kl}^\rho}{V_m} \right) \nabla (\mu_l - \mu_{Ag}) \right] \right]$
- ◆ Link with atomic mobilities β^ρ :

$$M_{kk}^\rho = x_k^\rho (1 - x_k^\rho) \beta^\rho, \quad M_{kl, k \neq l}^\rho = -x_k^\rho x_l^\rho \beta^\rho$$

- ◆ Link with interdiffusion coefficients: $M_{kl}^\rho = \frac{D_{kl}^\rho}{\frac{\partial^2 f^\rho}{\partial x_k^\rho \partial x_l^\rho}} = \frac{V_m D_{kl}^\rho}{\frac{\partial^2 G^\rho}{\partial x_k^\rho \partial x_l^\rho}}$

Phase field model: Evolution equations

- Diffusion

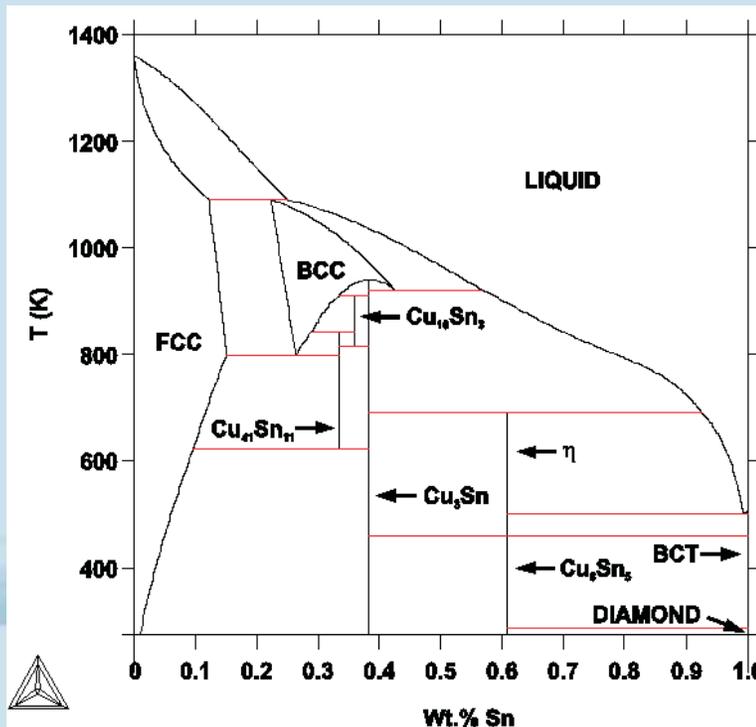
$$\frac{\partial x_k}{\partial t} = \nabla \cdot \left[\sum_l \left[\left(\sum_\rho \phi_\rho M_{kl}^\rho \right) \nabla \left(\frac{\partial f^\rho}{\partial x_l^\rho} \right) \right] \right]$$

- Interface movement

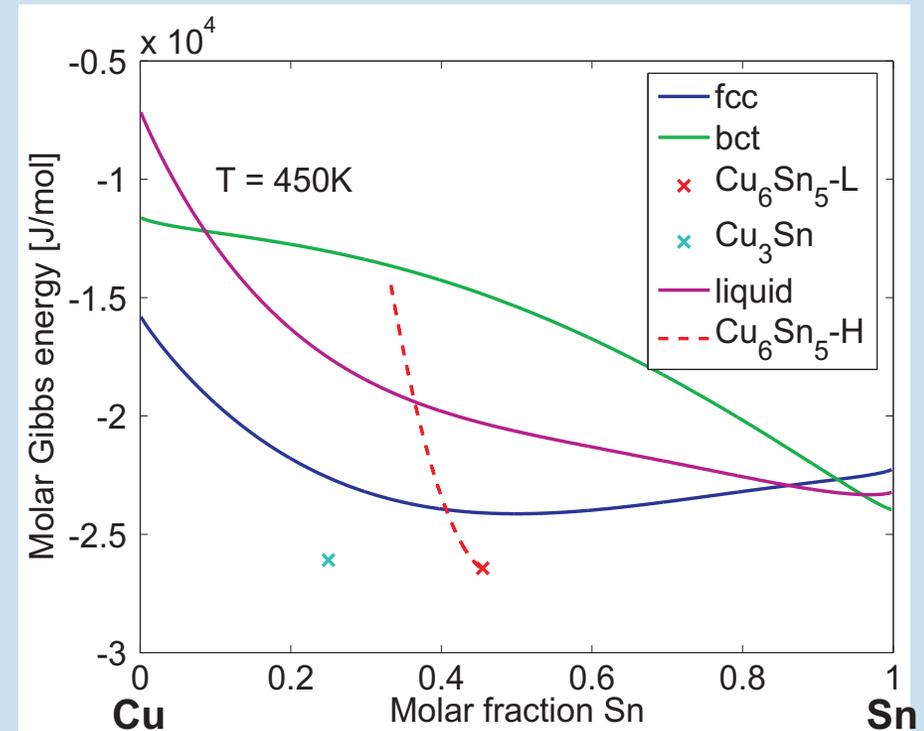
$$\frac{\partial \eta_{\rho,i}}{\partial t} = -L \frac{\delta F(\eta_{\sigma,j}, x_k)}{\delta \eta_\rho}$$



Phase diagram



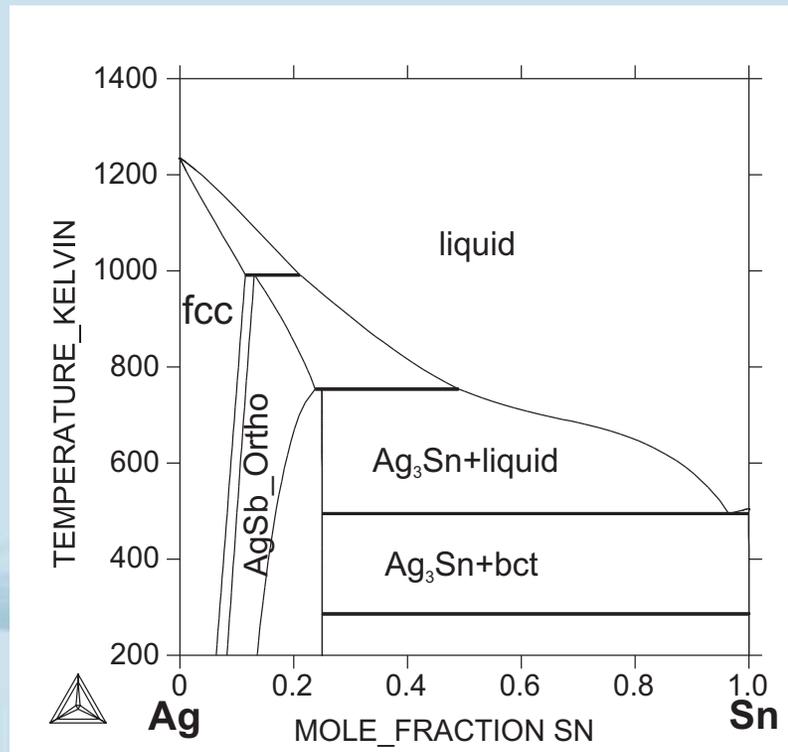
Molar Gibbs Energies at 450 K



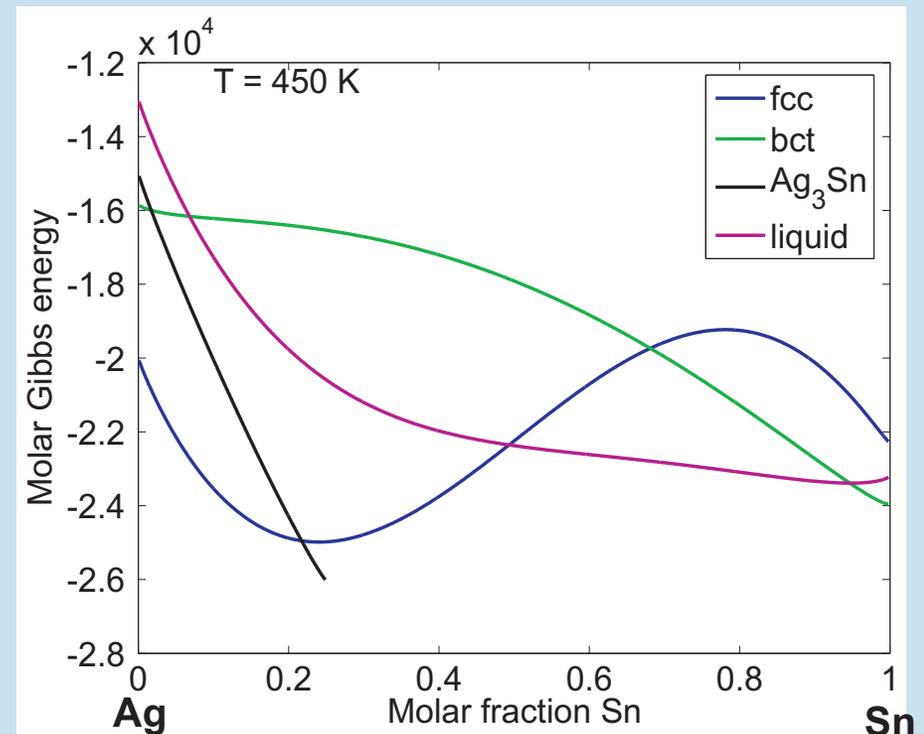
Bulk contribution phase-field energy: $f_{bulk} = \sum_{\rho} \phi_{\rho} \frac{G_m^{\rho}(x_k^{\rho})}{V_m}$

Diffusion equation: $\mu_k^{\rho} - \mu_{Ag}^{\rho} = \frac{\partial G^{\rho}}{\partial x_k}, \frac{\partial^2 G^{\rho}}{\partial x_k \partial x_l}, \quad k, l = Cu, Sn$

■ Phase diagram



■ Molar Gibbs energies at 450 K



■ Sublattice representation Ag_3Sn : $(Ag)_{0.75}(Ag, Sn)_{0.25}$

Model I: Stoichiometric phase

- Bulk contribution phase-field energy

$$f_{bulk} = \sum_{\rho} \phi_{\rho} \frac{G_m^{\rho}(x_k^{\rho})}{V_m} + \phi_{stoich} \frac{G_m^{stoich}}{V_m}$$

- ◆ Parallel tangent for solution phases

$$\frac{\partial f^{\rho}(x_k^{\rho})}{\partial x_k^{\rho}} = \frac{\partial f^{\sigma}(x_k^{\sigma})}{\partial x_k^{\sigma}},$$

$\forall k, \rho \neq \sigma$ solution phases

- ◆ Mass balance

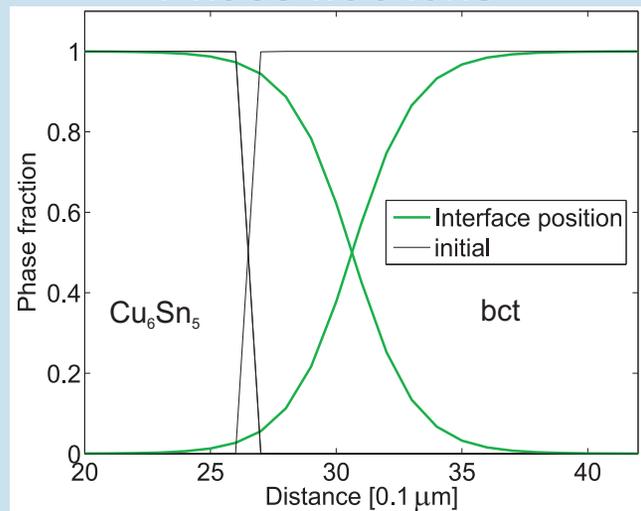
$$x_k - x_k^{stoich} = \sum_{\rho=sol} \phi_{\rho} (x_k^{\rho} - x_k^{stoich}), \quad \forall k$$

- $D_{kl}^{stoich} = M_{kl}^{stoich} = 0$

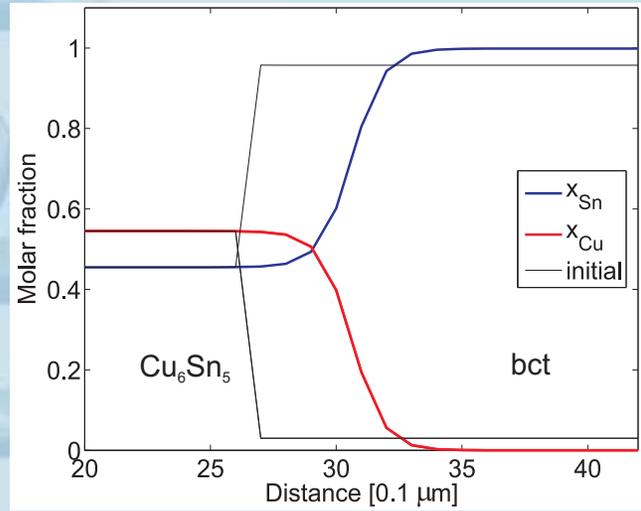
Model I: Stoichiometric phase

- Simulation precipitation IMC

Phase fractions

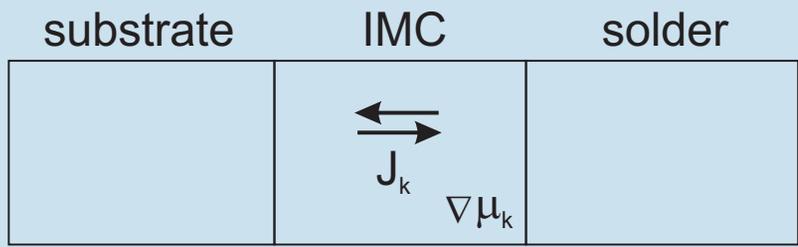


Molar fractions



- Growth IMC layer

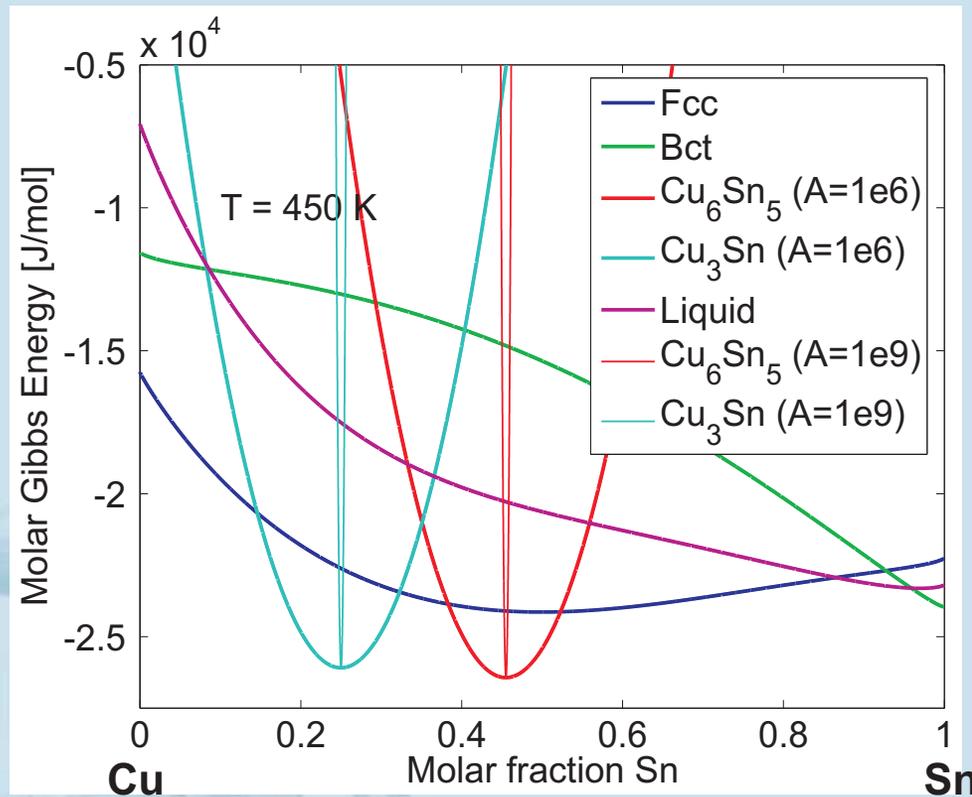
- ◆ Needs diffusion through IMC



$\Rightarrow G^{\rho}(x_k)$ needed to model $\nabla\mu_k$
the driving force for diffusion

Model II: Parabolic composition dependence

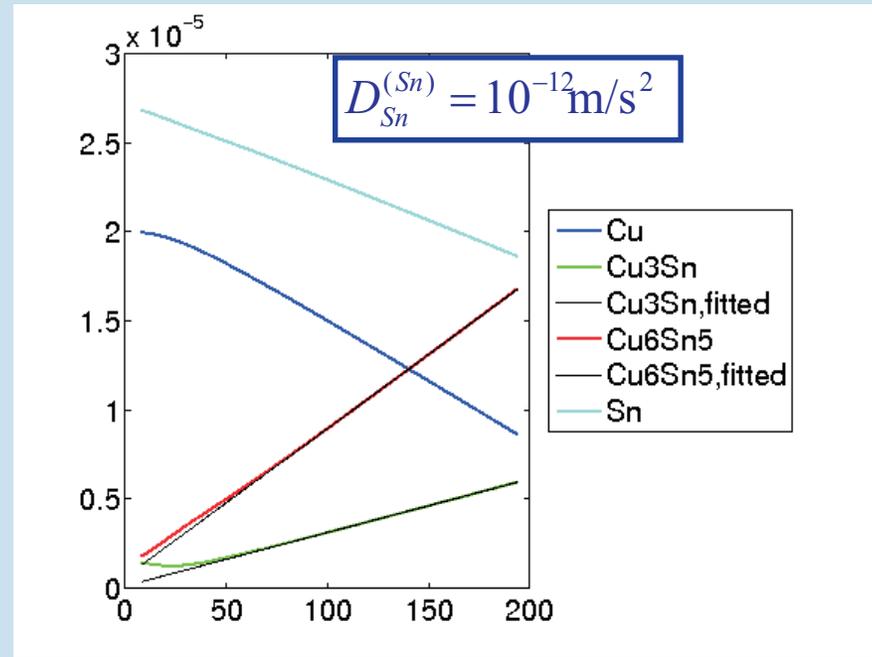
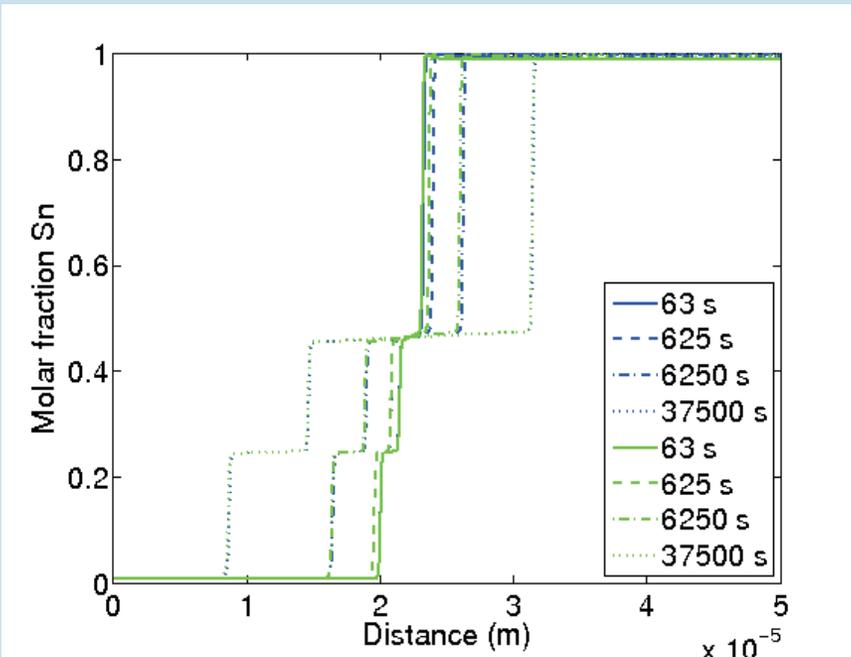
$$V_m f^{stoich} = \frac{A^{stoich}}{2} (x_{Sn} - x_{stoich,Sn})^2 + G_m^{stoich}(T = 450K) \quad (1)$$



- ◆ Steepness A^{stoich}
- ◆ Induces small shift in equilibrium
- ◆ $M_{Sn}^{stoich} = \frac{D_{Sn}^{stoich}}{A^{stoich}}$
(Composition independent)

[S.Y. Hu, J. Murray, H. Weiland, Z.-K. Liu, L.-Q. Chen, Comp. Coupl. Phase Diagr. Thermoch., 31 (2007) p 303]

Model II: Results



$$D_{Sn}^{(Cu)} = 10^{-25} \text{ m/s}^2$$

$$D_{Sn}^{CuSn} = 10^{-13} \text{ m/s}^2$$

$$D_{Sn}^{CuSn5} = 10^{-13} \text{ m/s}^2$$

$$D_{Sn}^{(Sn)} = 10^{-12} \text{ m/s}^2$$

$$D_{Sn}^{(Cu)} = 10^{-25} \text{ m/s}^2$$

$$D_{Sn}^{CuSn} = 10^{-13} \text{ m/s}^2$$

$$D_{Sn}^{CuSn5} = 10^{-13} \text{ m/s}^2$$

$$D_{Sn}^{(Sn)} = 10^{-14} \text{ m/s}^2$$

$$\Rightarrow k_{Cu3Sn} = 0.0301 \cdot 10^{-6}$$

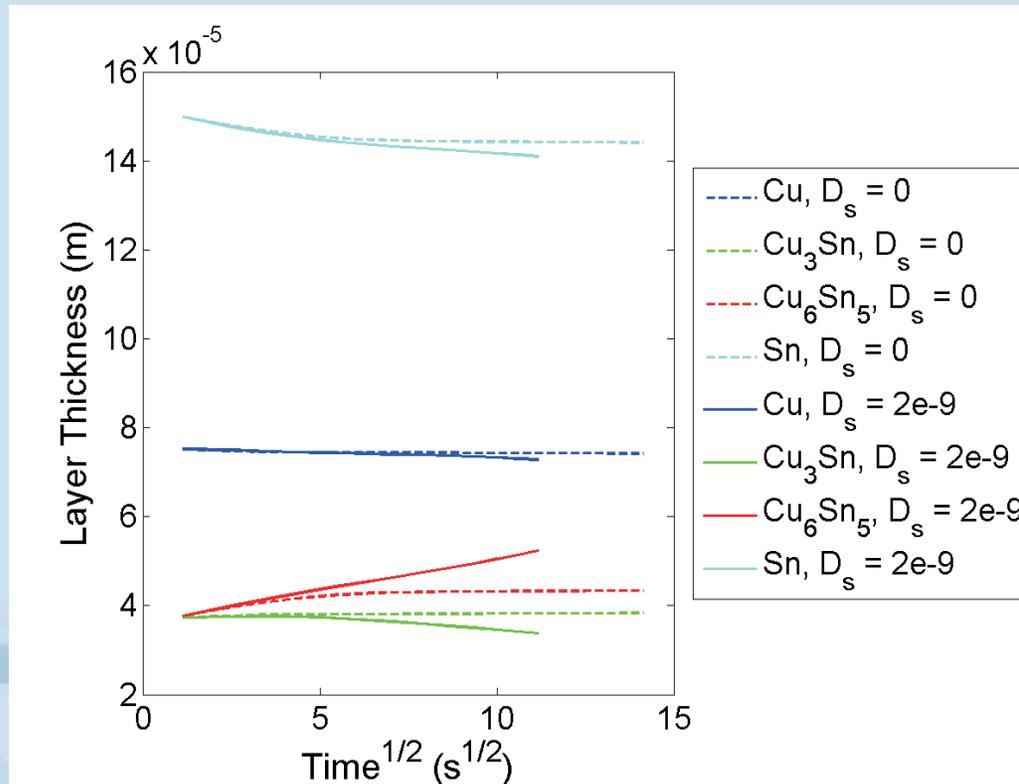
$$k_{Cu6Sn5} = 0.0833 \cdot 10^{-6}$$

$$\Rightarrow k_{Cu3Sn} = 0.0306 \cdot 10^{-6}$$

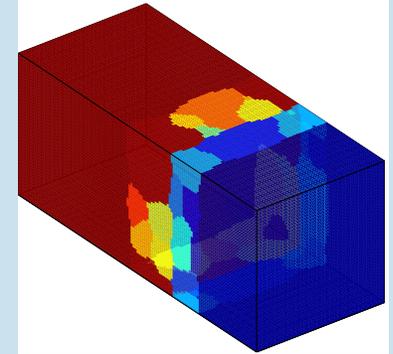
$$k_{Cu6Sn5} = 0.0849 \cdot 10^{-6}$$

Model II: Results

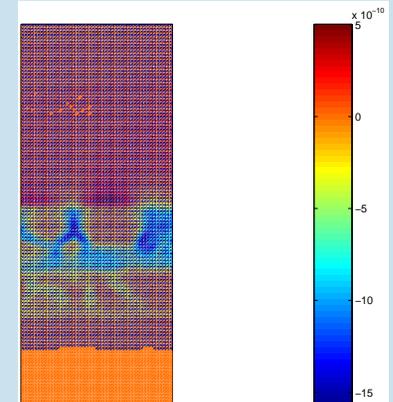
- With grain boundary diffusion



Grain structure



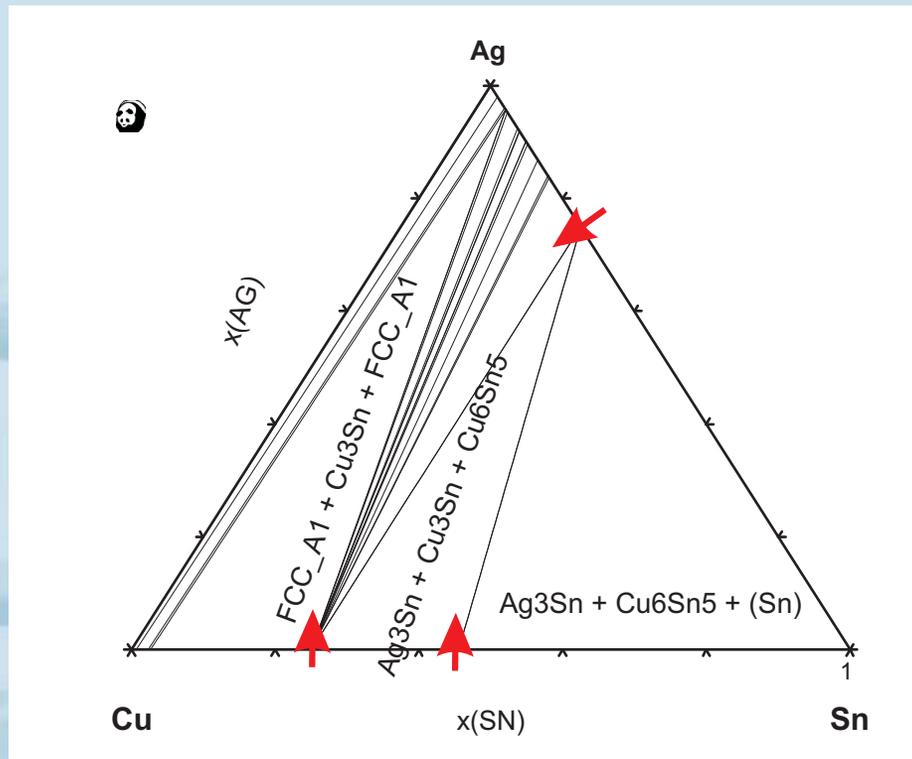
Vertical Flux of Sn



- $D_{Sn}^{fcc} = 2 \cdot 10^{-25} \text{ m}^2/\text{s}; D_{Sn}^{Cu3Sn} = 2 \cdot 10^{-15} \text{ m}^2/\text{s}; D_{Sn}^{Cu6Sn5} = 2 \cdot 10^{-15} \text{ m}^2/\text{s}; D_{Sn}^{bct} = 2 \cdot 10^{-12} \text{ m}^2/\text{s};$
- $D_{interf} = 2 \cdot 10^{-9} \text{ m}^2/\text{s}, \delta_{gb} = 1\text{nm}$

Model II: Parabolic composition dependence

$$\begin{aligned}
 V_m f^{stoich} = & \frac{A^{stoich}}{2} (x_{Sn} - x_{stoich,Sn})^2 \\
 & + \frac{A^{stoich}}{2} (x_{Ag} - x_{shift})^2 + G_m^{stoich}(T = 450K)
 \end{aligned}$$



- ◆ Steepness A^{stoich}
- ◆ Small shift in equilibrium
- ◆ $M_{kl}^{stoich} = \frac{D_{kl}^{stoich}}{A^{stoich}}$
- ◆ x_{shift} , e.g. = 0.001

Model III: Order-disorder CALPHAD description

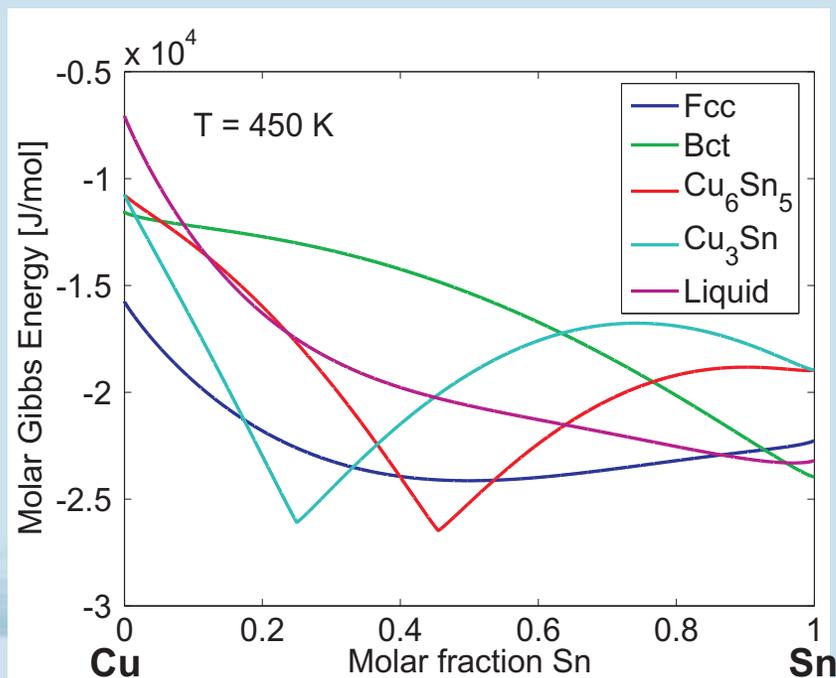
- Sublattice representation Cu_3Sn : $(\text{Ag}, \text{Cu}, \text{Sn})_{0.75}(\text{Ag}, \text{Cu}, \text{Sn})_{0.25}$
- Molar Gibbs Energy

$$\begin{aligned}
 G_m^{\text{Cu}_3\text{Sn}} = & x_{\text{Ag}} G_{\text{Ag}}^0 + x_{\text{Cu}} G_{\text{Cu}}^0 + x_{\text{Sn}} G_{\text{Sn}}^0 \\
 & + x_{\text{Ag}} x_{\text{Cu}} L_{\text{Ag},\text{Cu}} + x_{\text{Ag}} x_{\text{Sn}} L_{\text{Ag},\text{Sn}} \\
 & + x_{\text{Cu}} x_{\text{Sn}} L_{\text{Cu},\text{sn}} \\
 & + (y_{\text{Cu}}^1 y_{\text{Sn}}^2 - x_{\text{Cu}} x_{\text{Sn}}) G_{\text{Cu}_3\text{Sn}}^{\text{ord}} \\
 & + RT \left[0.75 (y_{\text{Ag}}^1 \ln(y_{\text{Ag}}^1) + y_{\text{Cu}}^1 \ln(y_{\text{Cu}}^1) \right. \\
 & \quad \left. + y_{\text{Sn}}^1 \ln(y_{\text{Sn}}^1)) \right. \\
 & \quad \left. + 0.25 (y_{\text{Ag}}^2 \ln(y_{\text{Ag}}^2) + y_{\text{Cu}}^2 \ln(y_{\text{Cu}}^2) \right. \\
 & \quad \left. + y_{\text{Sn}}^2 \ln(y_{\text{Sn}}^2)) \right]
 \end{aligned}$$

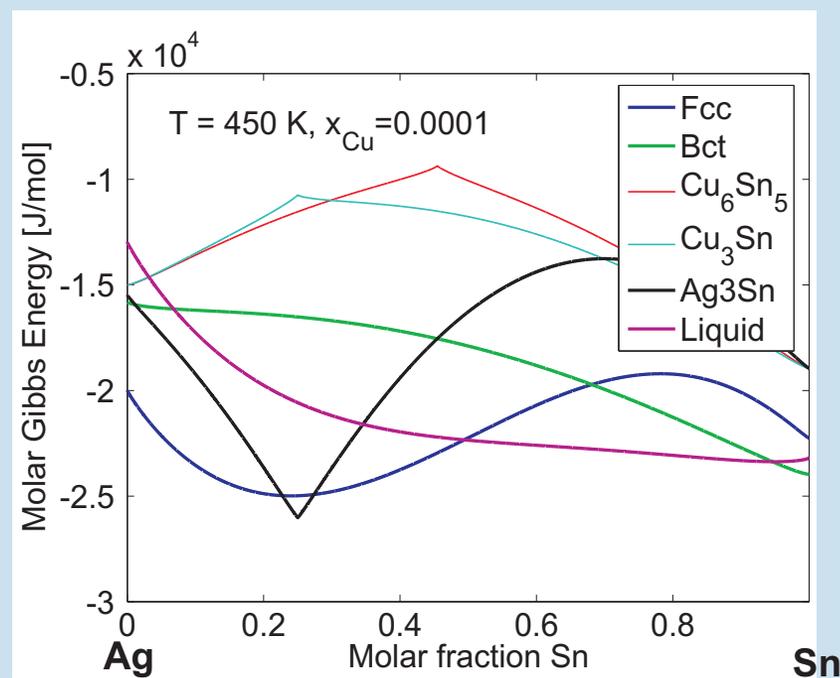
- $G_{\text{Ag}}^0 = \text{GHSER} + 5000$ and $L_{\text{Ag},\text{Cu}}, L_{\text{Ag},\text{Sn}}, L_{\text{Cu},\text{Sn}}$ and $G_{\text{Cu}_3\text{Sn}}^{\text{ord}}$ optimized

Model III: Order-disorder CALPHAD description

■ Cu-Sn, T=450K



■ Ag-Sn-0.01%Cu, T= 450 K



■ Miscibility gap is inherent

Model IV: Extended sublattice CALPHAD description

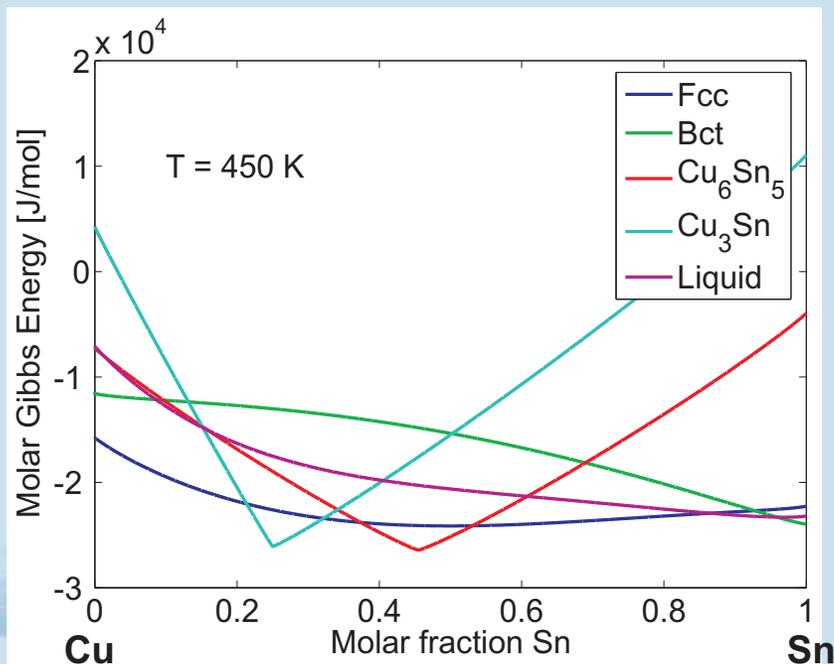
- Sublattice representation Cu_3Sn : $(\text{Ag}, \text{Cu}, \text{Sn})_{0.75}(\text{Ag}, \text{Cu}, \text{Sn})_{0.25}$
- Molar Gibbs Energy

$$\begin{aligned} G_m^{\text{Cu}_3\text{Sn}} = & y_{\text{Ag}}^1 y_{\text{Ag}}^2 G_{\text{Ag}}^0 + y_{\text{Cu}}^1 y_{\text{Cu}}^2 G_{\text{Cu}}^0 + y_{\text{Sn}}^1 y_{\text{Sn}}^2 G_{\text{Sn}}^0 \\ & + y_{\text{Cu}}^1 y_{\text{Sn}}^2 G_{\text{Cu}_3\text{Sn}}^0 + y_{\text{Sn}}^1 y_{\text{Cu}}^2 G_{\text{Sn}_3\text{Cu}}^0 \\ & + RT \left[0.75 (y_{\text{Ag}}^1 \ln(y_{\text{Ag}}^1) + y_{\text{Cu}}^1 \ln(y_{\text{Cu}}^1) \right. \\ & \quad \left. + y_{\text{Sn}}^1 \ln(y_{\text{Sn}}^1)) \right. \\ & \quad \left. + 0.25 (y_{\text{Ag}}^2 \ln(y_{\text{Ag}}^2) + y_{\text{Cu}}^2 \ln(y_{\text{Cu}}^2) \right. \\ & \quad \left. + y_{\text{Sn}}^2 \ln(y_{\text{Sn}}^2)) \right] \end{aligned}$$

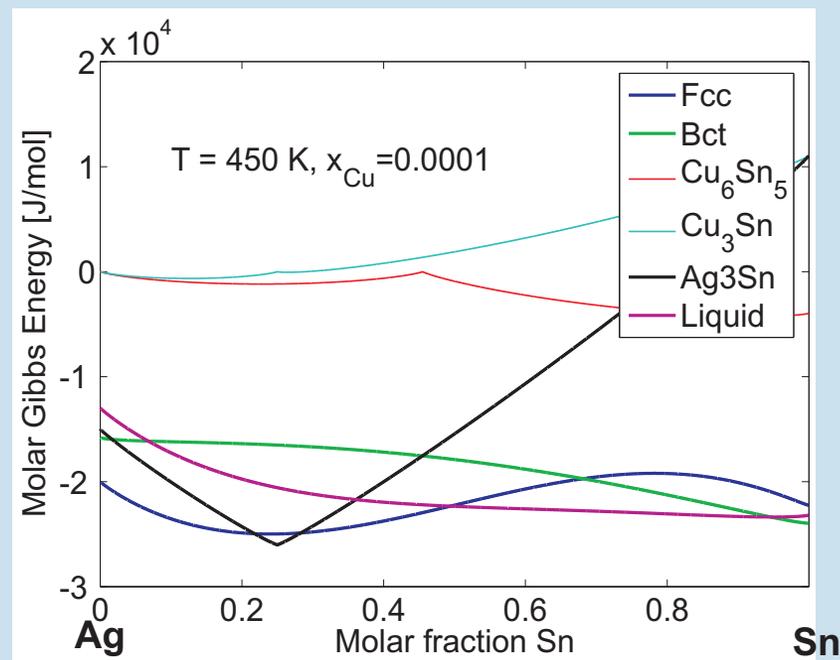
using $G_{\text{Sn}_3\text{Cu}}^0 = G_{\text{Cu}}^0 + G_{\text{Sn}}^0 - G_{\text{Cu}_3\text{Sn}}^0$

Model IV: Extended sublattice CALPHAD description

■ Cu-Sn, T=450K

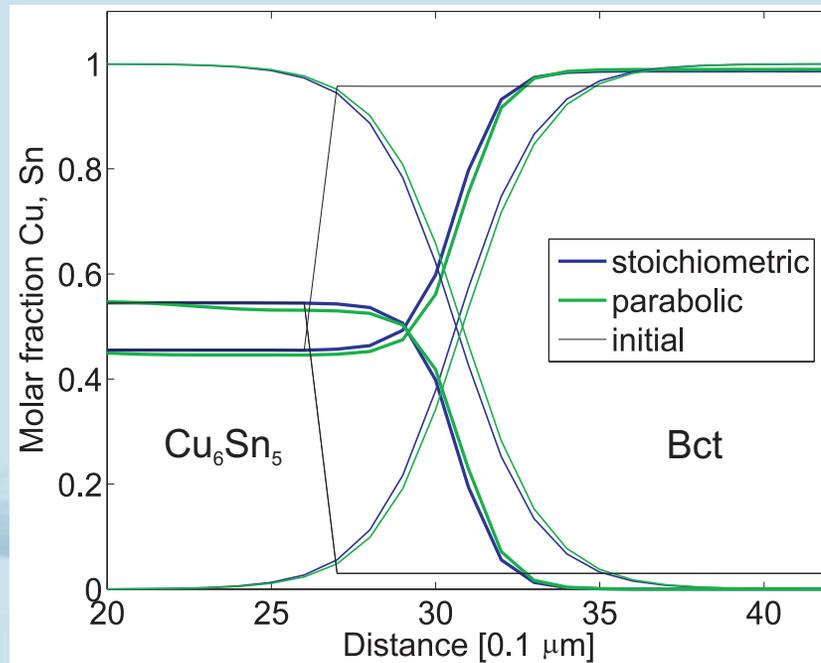


■ Ag-Sn-0.01%Cu, T= 450 K

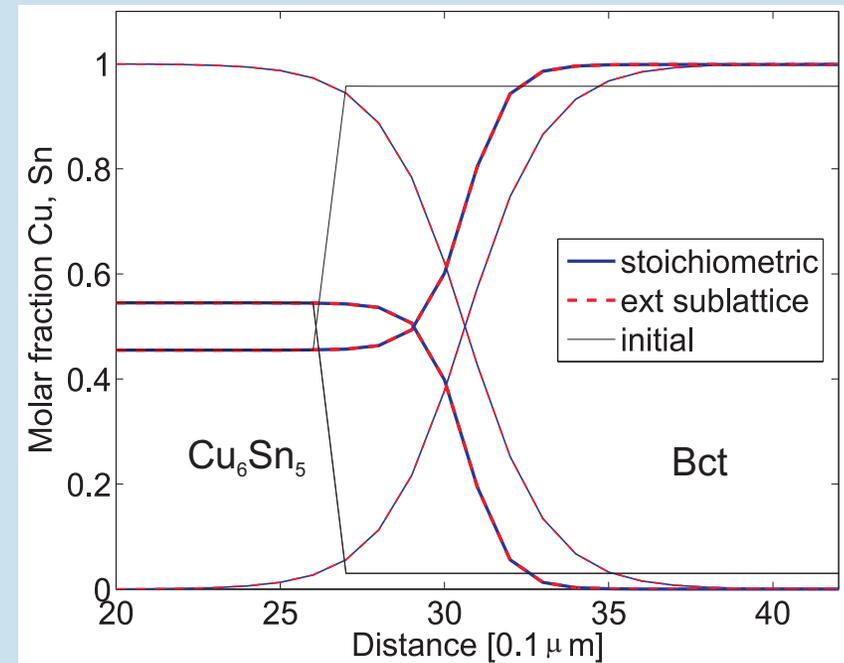


Comparison: Growth Cu_6Sn_5 from supersaturated Bct

- Comparison stoichiometric (I) – parabolic (II)



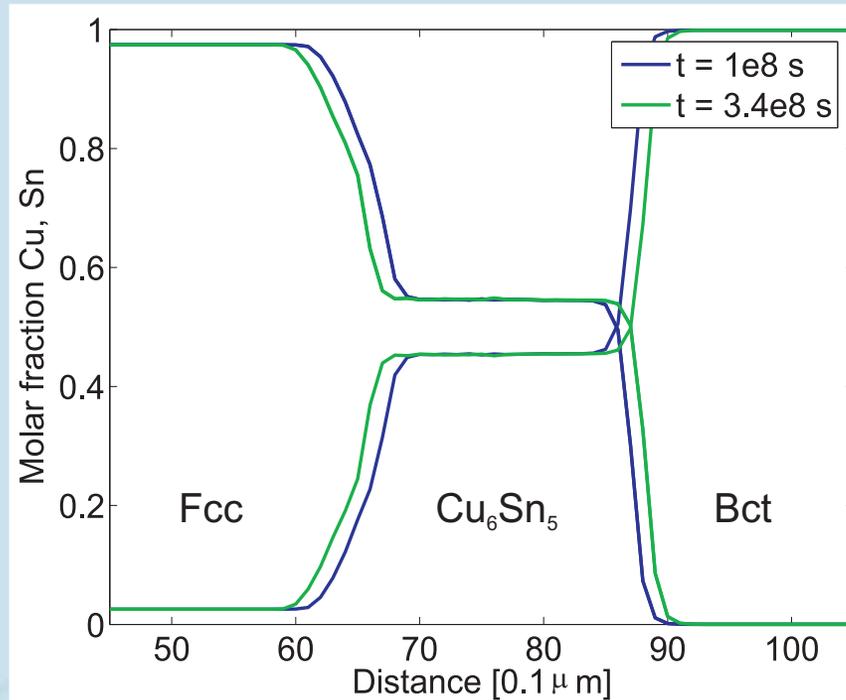
- Comparison stoichiometric (I) – sublattice (II)



- $M^{\text{Cu}_6\text{Sn}_5} = 0$

- $M_{kk}^{\text{bct}} = \beta^{\text{bct}} x_k^{\text{bct}} (1 - x_k^{\text{bct}}), M_{kl,k \neq l}^{\text{bct}} = -\beta^{\text{bct}} x_k^{\text{bct}} x_l^{\text{bct}}$

Model IV: Growth Cu_6Sn_5 between Fcc and Bct



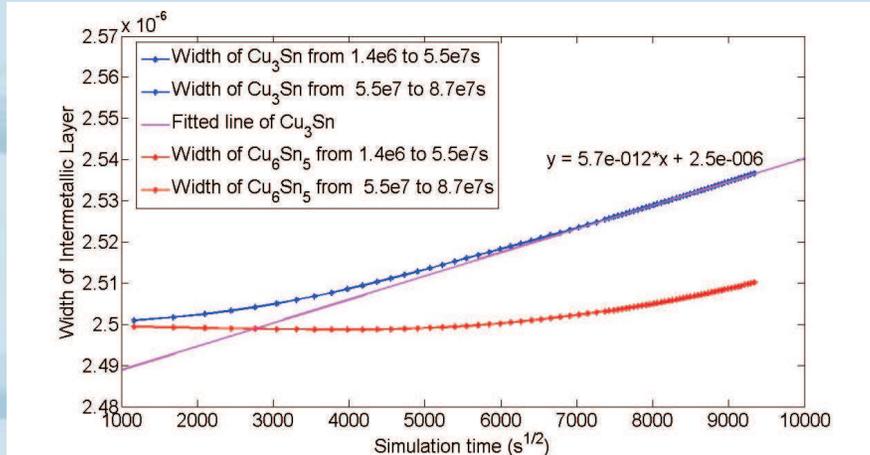
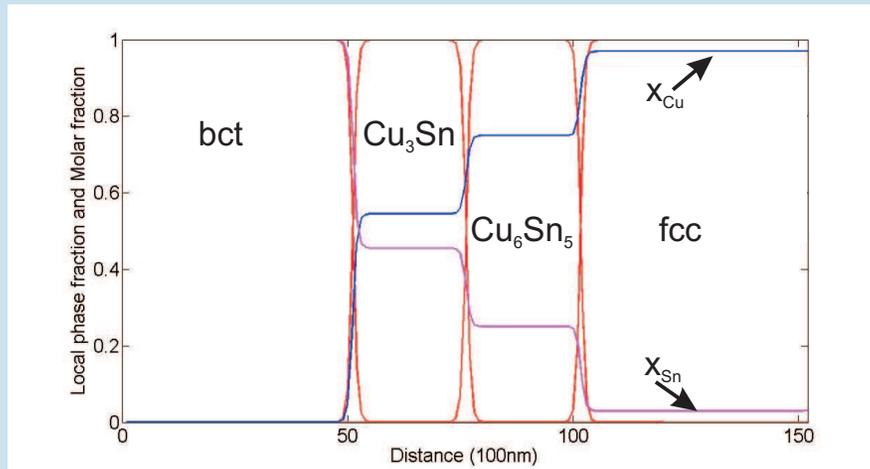
Diffusion equation

$$\frac{\partial x_k}{\partial t} = \nabla \cdot \left[\sum_l \left[\left(\sum_\rho \phi_\rho M_{kl}^\rho \right) \nabla \left(\frac{\partial f^\rho}{\partial x_l^\rho} \right) \right] \right]$$

- $M_{kk}^{bct/fcc} = \beta^{bct/fcc} x_k (1 - x_k)$; $M_{kl, k \neq l}^{bct/fcc} = -\beta^{bct/fcc} x_k x_l$
- $M^{Cu_6Sn_5} = \beta^{Cu_6Sn_5} (0.545 y_k^1 (1 - y_k^1) + 0.455 y_k^2 (1 - y_k^2))$,
 $M_{kl, k \neq l}^{Cu_6Sn_5} = -\beta^{Cu_6Sn_5} (0.545 y_k^1 y_l^1 + 0.455 y_k^2 y_l^2)$
- β^ρ estimated based on interdiffusion coefficients of [A. Paul, C. Ghosh and W.J. Boettinger, Metall. Mater. Trans. A, 42A (2011) p952].

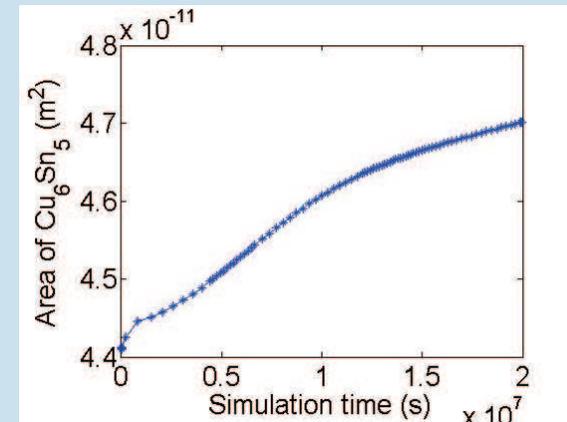
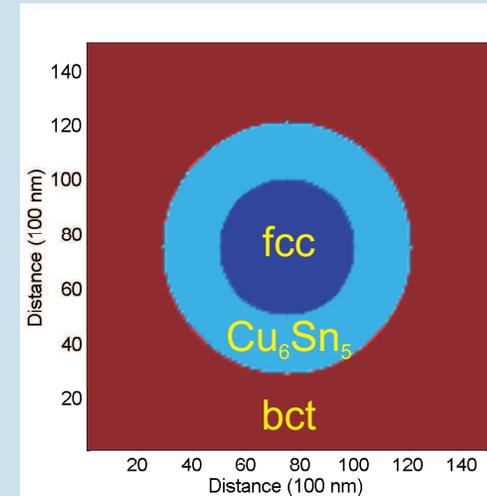
Model IV: Growth rate Cu_3Sn and Cu_6Sn_5

1D system



Cu_3Sn grows faster than Cu_6Sn_5 !

2D system



- Form of the Gibbs energies influences microstructure simulations of interdiffusion phenomena at interfaces (diffusion couples)
 - ◆ Determines which IMC grows fastest/first
- For a general coupling of phase-field with CALPHAD, an extended sublattice model is most suitable
 - ◆ Or order-disorder model if based on physics
- Presented approaches also valuable for sharp interface diffusion techniques, e.g. DICTRA
- Databases with extended sublattice representations can be improved iteratively